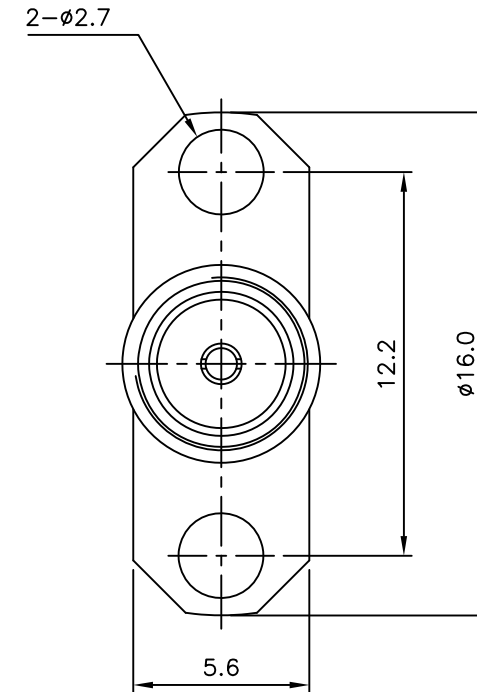
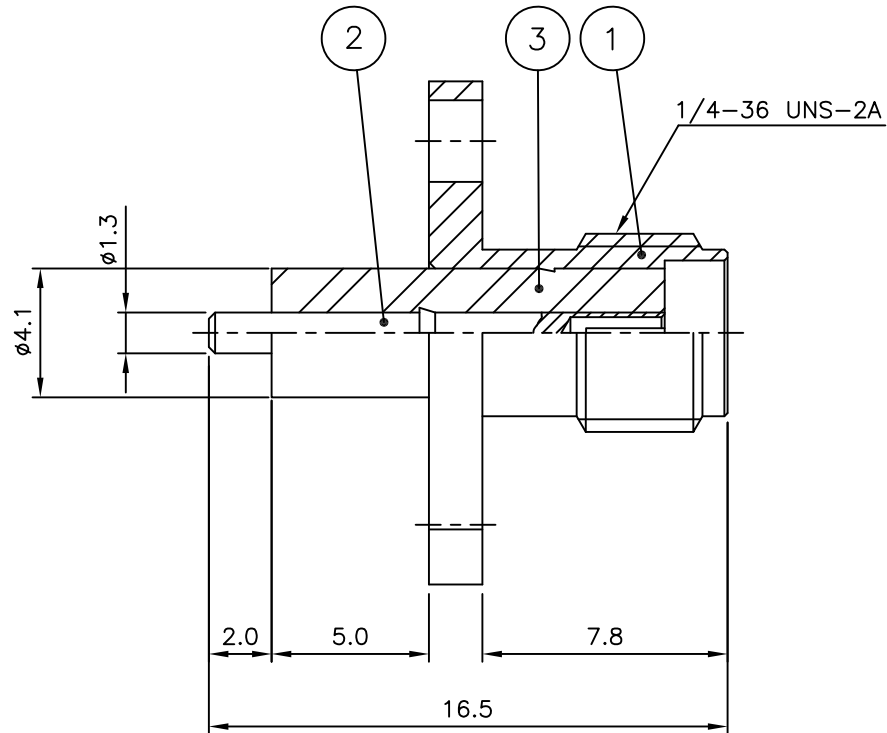
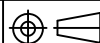


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2002.05.30.
1	공용화 (PIN E2235->E2362 변경)	E.H.KIM	B.H.AHN	2004.08.20.
2	조립성 향상 (TEFLON H2020 -> H2132 변경)	E.H.KIM	K.Y.KIM	2004.09.08.
3	절연체 공용화로 인한 코드 변경	S.Y.EUN	I.C.KIM	2020.12.24.



3	INSULATOR	1	TEFLON		DIN02077-N/1 DIN00121-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT00224-5/1
1	BODY	1	MBsBD	Gold Plate	DBD00347-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2020. 12. 24.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY I.C.KIM			
MATERIAL _____	CHECKED BY		TITLE SMA50 SOLDER END JS-2H		
	DRAWN BY S.Y.EUN				
FINISH _____	SCALE 4/1	UNIT mm		DWG NO. CN01240-7/1	SHEET 1 of 1
				REVISION 3	